## PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1 Stylesheet Version v1.2 EPAS ID: PAT6236994

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

#### **CONVEYING PARTY DATA**

Name	Execution Date
YI-HSING HSIAO	05/22/2020
JUI-CHENG HUANG	05/27/2020

#### **RECEIVING PARTY DATA**

Name:	TAIWAN SEMICONDUCTOR MANUFACTURING CO., LTD.
Street Address:	NO.8, LI-HSIN RD. 6, HSINCHU SCIENCE PARK,
City:	HSINCHU
State/Country:	TAIWAN
Postal Code:	300-78

### **PROPERTY NUMBERS Total: 1**

Property Type	Number
Application Number:	16944140

#### **CORRESPONDENCE DATA**

**Fax Number:** (949)391-4699

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent

using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Phone: 886223692800
Email: usa@jcipgroup.com

Correspondent Name: JCIPRNET

Address Line 1: 8F-1, NO. 100, ROOSEVELT RD. SEC. 2,

Address Line 4: TAIPEI, TAIWAN 100404

ATTORNEY DOCKET NUMBER:	096557-US-PA
NAME OF SUBMITTER:	BELINDA LEE
SIGNATURE:	/Belinda Lee/
DATE SIGNED:	08/05/2020

#### **Total Attachments: 3**

source=096557\_del-assn#page1.tif source=096557\_del-assn#page2.tif source=096557\_del-assn#page3.tif

PATENT 506190255 REEL: 053414 FRAME: 0389

P20193627US00 096557-US-PA

# DECLARATION AND ASSIGNMENT

## FOR UTILITY OR DESIGN PATENT APPLICATION

The above-identified application was made or authorized to be made by me.

I believe I am the original inventor or an original joint inventor of a claimed invention in the application.

The undersigned hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.

- 1 -

P20193627US00 096557-US-PA

## **DECLARATION AND ASSIGNMENT** FOR UTILITY OR DESIGN PATENT APPLICATION

WHEREAS, the undersigned has invented certain new and useful improvements described in the application identified.

WHEREAS, 1. Taiwan Semiconductor Manufacturing Co., Ltd.

of

No.8, Li-Hsin Rd. 6, Hsinchu Science Park, Hsinchu, Taiwan 300-78, R.O.C.

hereinafter referred to as ASSIGNEE, is desirous of acquiring the undersigned's interest in the said invention and application and in any U.S. Letters Patent which may be granted on the same:

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN: Be it known that, for good and valuable consideration, receipt of which is hereby acknowledged by the undersigned, the undersigned has/have sold, assigned and transferred, and by these presents does/do sell, assign and transfer unto the said Assignee, and Assignee's successors and assigns, all his/her/their rights, title and interest in and to the said invention and application and all future improvements thereon, and in and to any Letters Patent which may hereafter be granted on the same in the United States, the said rights, title and interest to be held and enjoyed by said Assignee as fully and exclusively as it would have been held and enjoyed by said the undersigned had this Assignment and transfer not been made, to the full end and term of any Letters Patent which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.

The undersigned further agrees/agree that he/she/they will, without charge to said Assignee, but at Assignee's expense, cooperate with Assignee in the prosecution of said application and/or applications, execute, verify, acknowledge and deliver all such further papers, including applications for Letters Patent and for the reissue thereof, and instruments of assignment and transfer thereof, and will perform such other acts as Assignee Lawfully may request, to obtain or maintain Letters Patent for said invention and improvement, and to vest title thereto in said Assignee, or Assignee's successors and assigns.

P20193627US00 096557-US-PA

**RECORDED: 08/05/2020** 

hhaiaok 2020/05/22 16:26:25

# DECLARATION AND ASSIGNMENT FOR UTILITY OR DESIGN PATENT APPLICATION

Signature: Ti-Hsing Hsiao Date: 05/22/2020			
Legal Name of Sole or First Inventor: Yi-Hsing Hsiao			
Residence: Hsinchu, Taiwan			
Mailing Address: c/o No.8, Li-Hsin Rd. 6, Hsinchu Science Park, Hsinchu, Taiwan 300-78, R.O.C.			
Signature: Jui-cheng Huang Date: 0,6/27/2020			
Legal Name of Additional Joint Inventor, if any: Jui-Cheng Huang			
Residence: Hsinchu City, Taiwan			
Mailing Address: c/o No.8, Li-Hsin Rd. 6, Hsinchu Science Park, Hsinchu, Taiwan 300-78, R.O.C.			

- 3 -